Devcon DFense Blok™ Surface Wetting Agent

Epoxy; Epoxide

Devcon

Message:

Thixotropic epoxy gel system that improves ease of application and cured adhesion properties (shear, peel, impact) of Devcon® DFense Blok™ abrasion resistant product.
Intended Use:
Apply to substrate surface prior to using DFense Blok™ for better adhesion.
Product Features:
Requires no waiting to apply topcoat
Excellent chemical resistance
Non-sagging

General Information	
Features	thixotropic Good chemical resistance
Appearance	Orange
Forms	Gel

Physical	Nominal Value	Unit	Test Method
Specific Volume	0.892	cm^3/g	
Solid content-by Volume	100	%	
Temperature Resistance	149	°C	
Tensile Shear Adhesion	18.0	MPa	ASTM D1002
Density [1]	1.10	g/cm^3	

Hardness	Nominal Value	Unit	Test Method
Durometer Hardness (Shore D)	71		ASTM D2240

Mechanical	Nominal Value	Unit	Test Method
Flexural Strength	46.2	MPa	ASTM D790
Compressive Strength	34.7	MPa	ASTM D695

Thermoset	Nominal Value	Unit	Test Method
Thermoset Components			
Component a	Mixing ratio by weight: 100 Mixing ratio by capacity: 2.0		
Component B	Mixing ratio by weight: 44 Mixing ratio by capacity: 1.0		
Pot Life (22°C)	12 - 15	min	

Additional Information	Nominal Value	Unit	Test Method

Cured 7 days @ 75°F

Uncured Properties	Nominal Value	Unit	Test Method
Curing Time	16	hr	
NOTE			
1.	Mixed		